

Application No.: 10/612,804

Supplemental Amendment dated: September 9, 2005

Reply to Office Action dated: June 10, 2005

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

1-2 (Cancelled)

3. (Original) A method, comprising:

forming a conductive bump on one of a die and a substrate;

forming a non-conductive pocket on the other of said die and substrate; and

contacting the bump with the non-conductive pocket; and

curing the bump and the non-conductive pocket to form a covalently bonded laminate structure.

4. (Original) The method of claim 3, wherein said step of forming the conductive bump includes forming the bump using a polymer.

5-17 (Cancelled)

18. (Original) A method for making a flip chip apparatus, comprising:

forming a plurality of electrically conductive polymer bumps on one of a die and a substrate;

forming an electrically non-conductive film around each of a plurality of contact pads on

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other of said die and substrate;

partially curing the bumps and the film; and

contacting the bumps with the contact pads, and curing the bumps and the non-conductive film to form a covalently bonded laminate structure.

19. (Original) The method of claim 18 wherein the bumps and the film being formed from materials allowing control of the degree of latency of the bumps.

20. (Original) The method of claim 18, wherein the materials include benzocyclobutene.

21. (Original) The method of claim 18, wherein the covalently bonded structure being formed of materials having equivalent coefficients of thermal expansion.

22. (Original) The method of claim 18, wherein said step of forming the polymer bumps includes forming the bumps using one of spin coating and stencil printing.

23-27 (Cancelled)